

REMARKS

The Examiner has divided the pending claims into two groups, that is, claims 1-12 into Group I and claims 13-20 into Group II, and imposed a restriction requirement between the groups. The Applicants elect to prosecute the invention of Group I, claims 1-12, in this application. Please withdraw claims 13-20 from further consideration in this application, without prejudice to pursuing the withdrawn claims in a divisional or other continuing application. The Applicants plan on filing a divisional application to prosecute the invention of claims 13-20.

The Applicants have also used this opportunity to add claims 21-28 to replace the cancelled claims 13-20. These claims are similar to Group I in that they are method claims directed to securing a printed circuit board to a surface. Claims 1-12 are directed to attaching the circuit board to an "underlying surface" (except dependant claims 7-8 that specify that the "underlying surface" is a top surface of a rigidizer). New claims 21-28 specific recite a top surface of a rigidizer. Consideration of these newly added claims is respectfully requested.

The Examiner has also indicated that within Group I that the application is directed to patentably distinct species of the claimed invention: the various species of adhesive employed cured in the process by heat (claim 10), ultraviolet radiation exposure (claim 11), and multiple curing mechanisms wherein at least two of the curing mechanism are different from each other (claim 12). The newly added claims would likely fall within the same category under this analysis: the various species of adhesive employed cured in the process by heat (claim 26), ultraviolet radiation exposure (claim 27), and multiple curing mechanisms wherein at least two of the curing mechanism are different from each other (claim 28). The Applicants identify and elect the first species – adhesive employed cured in the process by heat (claims 10, 26).

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In view of the foregoing, the Applicants respectfully request that the restriction requirement be withdrawn upon reconsideration of the application. If the Examiner feels that a telephone conference would be helpful to resolve any remaining issues, the Examiner is respectfully requested to contact the undersigned attorney at (847) 538-7103.

Respectfully submitted,
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APPENDIX A

Version with Markings to Show Changes Made

IN THE CLAIMS

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Claims 21-28 have been added as follows:

21. A method for securing a printed circuit board to a rigidizer comprising steps of:
applying a liquid adhesive to a top surface of the rigidizer;
curing the liquid adhesive during a first curing stage, after application of the liquid adhesive,
to produce a partially cured liquid adhesive;
placing the printed circuit board on the partially cured liquid adhesive; and
curing the partially cured liquid adhesive during a second curing stage to produce a fully
cured liquid adhesive.
22. The method of claim 21, wherein the step of applying the liquid adhesive to the top surface of
the rigidizer comprises a step of screening the liquid adhesive onto the top surface of the rigidizer.
23. The method of claim 21, wherein the liquid adhesive is a dual-cure system adhesive.
24. The method of claim 21, wherein the step of curing of the liquid adhesive during a first stage
produces a tacky adhesive that spreads, at most, a negligible amount when the printed circuit board is
placed on the partially-cured liquid adhesive.
25. The method of claim 21, further comprising a step of bending the printed circuit board and
the rigidizer after the second cure of the liquid adhesive.
26. The method of claim 21, wherein the liquid adhesive is a heat-curable liquid adhesive,
wherein the first cure comprises applying a first heating stage to the liquid adhesive and wherein the
second cure comprises applying a second heating stage to the liquid adhesive.

27. The method of claim 21, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

28. The method of claim 21, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.

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